

The listing of claims replaces the previous version, and the listing of claims:

LISTING OF CLAIMS

1. (currently amended) A plasma-enhanced processing apparatus, comprising;

a process chamber in which a substrate is processed,

a pumping system ~~that pumps~~ communicating with said process chamber for exhausting gas in the process chamber,

120 a gas-introduction system that introduces process gas into said process chamber,

a plasma-generation means that generates plasma in said process chamber by applying energy to said process gas,

a substrate holder that holds said substrate in said process chamber, and

wherein an opposite electrode disposed in the process chamber to face facing to said substrate held by said substrate holder is provided, and the opposite electrode including a main body, a front board disposed on the main body, and comprises a clamping mechanism that clamps the front board to support said front board onto the main body so that the front board is pressed onto the main body to have a uniform thermal contact at a side opposite to a side where the plasma is generated.

2. (currently amended) A plasma-enhanced processing apparatus as claimed in claim 1, wherein, said opposite electrode comprises a main body, and includes a cooling mechanism that cools said front board via said main body.

3. (currently amended) A plasma-enhanced processing apparatus as claimed in claim 1, wherein, said clamping mechanism includes ~~clamps the periphery of said front board by a clamping plate in surface contact with said front board to clamp a periphery of the front board.~~

4. (currently amended) A plasma-enhanced processing apparatus as claimed in claim 3, wherein, said front board has a step at said periphery that is sandwiched by said main board and said clamping plate, and said clamping plate is flush with said front board.

5. (currently amended) A plasma-enhanced processing apparatus as claimed in claim 1, further comprising, a protector covering a surface of said clamping mechanism, wherein so that said surface is not exposed to said plasma.

6. (currently amended) A plasma-enhanced processing apparatus as claimed in claim 4 5, wherein, said clamping mechanism includes ~~clamps the periphery of said front board by~~ a clamping plate in surface contact on with said front board to clamp a periphery of the front board, and said protector is flush with said front board.

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7. (currently amended) A plasma-enhanced processing apparatus as claimed in claim 6, wherein, said front board is made of silicon poly-crystal or silicon mono-crystal.

8. (currently amended) A plasma-enhanced processing apparatus as claimed in claim 3, wherein, said clamping plate is screwed on a member except said front board to press said front board onto said main body, and with screwing torque is of 1Nm or more.

9. (currently amended) A plasma-enhanced processing apparatus as claimed in claim 6, wherein, said clamping plate is screwed on a member except said front board to press said front board onto said main body, and with screwing torque is of 1Nm or more.

10. (currently amended) A plasma-enhanced processing apparatus as claimed in claim 6, wherein, further comprising a sheet made of carbon is inserted between said main body and said front board.

11. (new) A plasma-enhanced processing apparatus as claimed in claim 1, wherein said clamp mechanism clamps said front board by pressure along a direction of thickness of the front board.

12. (new) A plasma-enhanced processing apparatus as claimed in claim 1, further comprising a sheet between the main body and the front board.

13. (new) A plasma-enhanced processing apparatus as claimed in claim 12, wherein said sheet is made of carbon.

14. (new) A plasma-enhanced processing apparatus as claimed in claim 2, wherein said cooling mechanism prevents increase of temperature of the front board in operation.

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15. (new) A plasma-enhanced processing apparatus as claimed in claim 1, wherein said opposite electrode further includes an insulation casing disposed around the main body, and said front board has a stepped portion at a periphery thereof, said clamping mechanism engaging the stepped portion to be flush with a surface of the front board and being fixed to the insulation casing.

16. (new) A plasma-enhanced processing apparatus as claimed in claim 15, wherein said clamping mechanism further includes a clamping plate engaging the stepped portion of the front board, and a screw for fixing the clamping plate from a lower surface thereof to the insulation casing.

17. (new) A plasma-enhanced processing apparatus as claimed in claim 16, further comprising an L-shaped protector covering the screw and at least a part of the clamping plate, said L-shaped protector being fixed to the insulation casing at a side thereof.

IN THE DRAWINGS

In Fig. 2, add a sheet 5' between a front board 5 and a main body 61, which is explained in paragraph 0043 of the specification.